

ALD



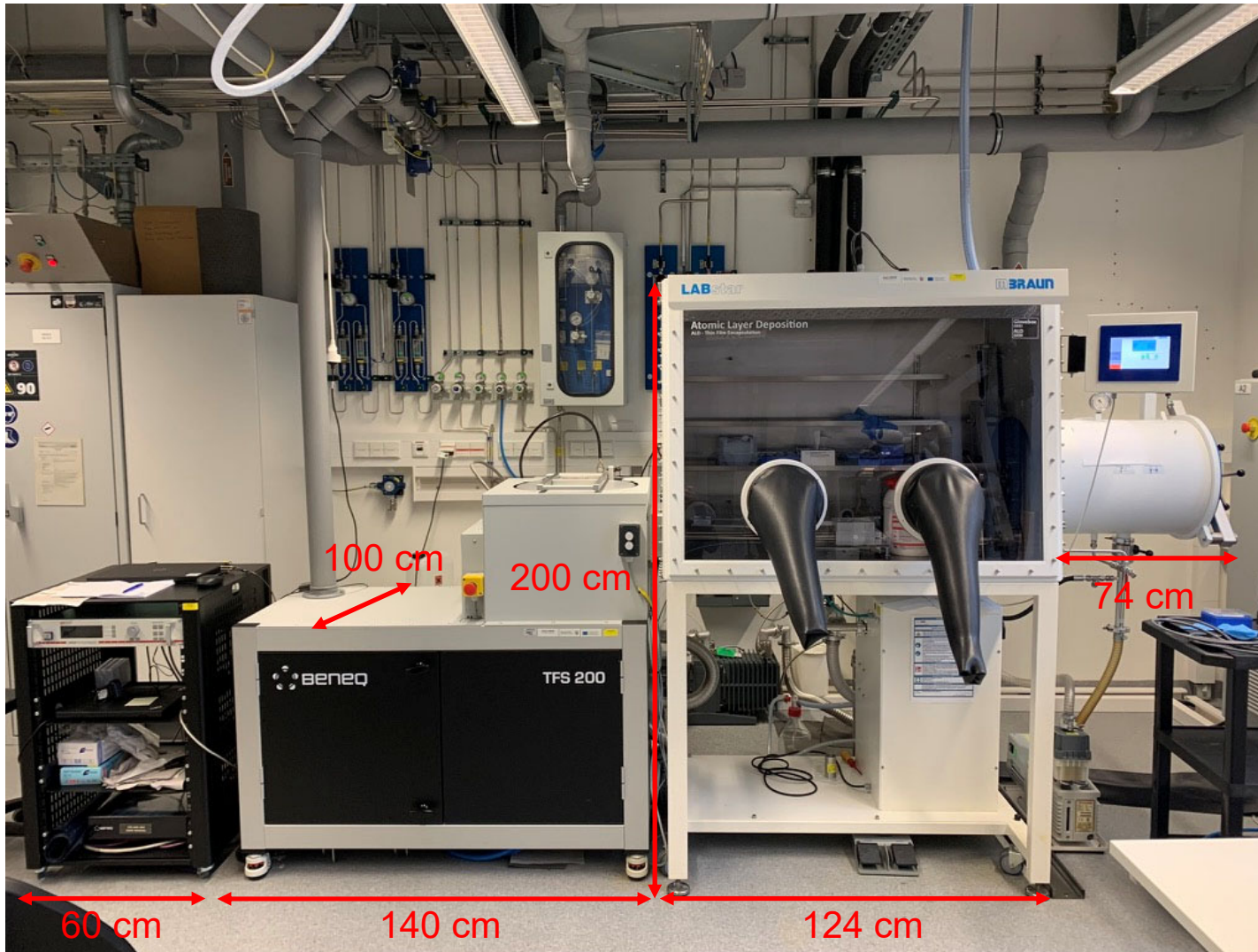
Research Atomic Layer Deposition
(ALD) Thin Film System TFS 200

producer: BENEQ
date of purchase: 15.04.2014
original net price: 280.000 €
price: to be discussed

Features

- **thermal** or **plasma** enhance ALD
- **gas**, **liquid** or **solid** precursors and carrier gasses, e.g. TMA, TiCl_4 , DEZ, TEMAH, H_2O , NH_3 , O_2 , N_3 , Ar
- up to 4 liquid sources
- up to 8 gas lines
- up to **200 mm wafers**
- substrate temperature range **25°C – 350°C**
- class 100 (ISO 5) **clean-room** compatible
- water cooled cold-wall vacuum chamber + hot wall reaction chamber
- **glovebox** for high purity sample loading

Approximate dimensions



Dimensions:

total **width**: ca. 330 cm

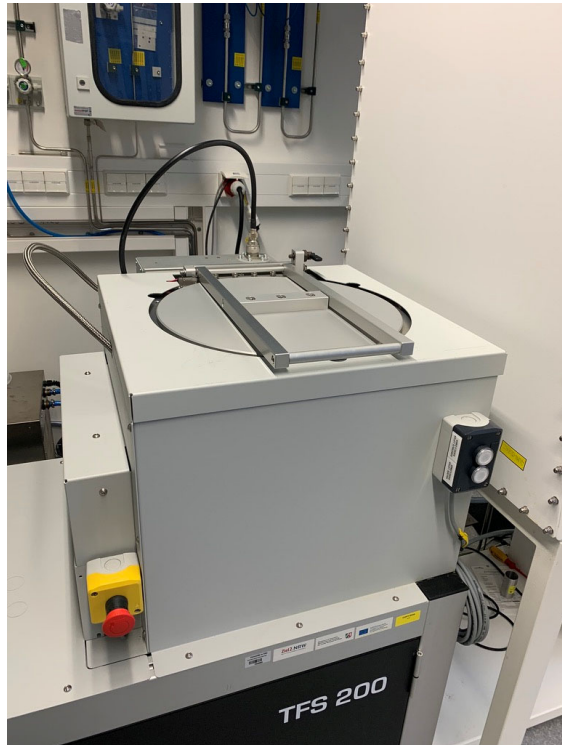
(+ laptop trolley 60cm)

total **depths**: ca. 100 cm

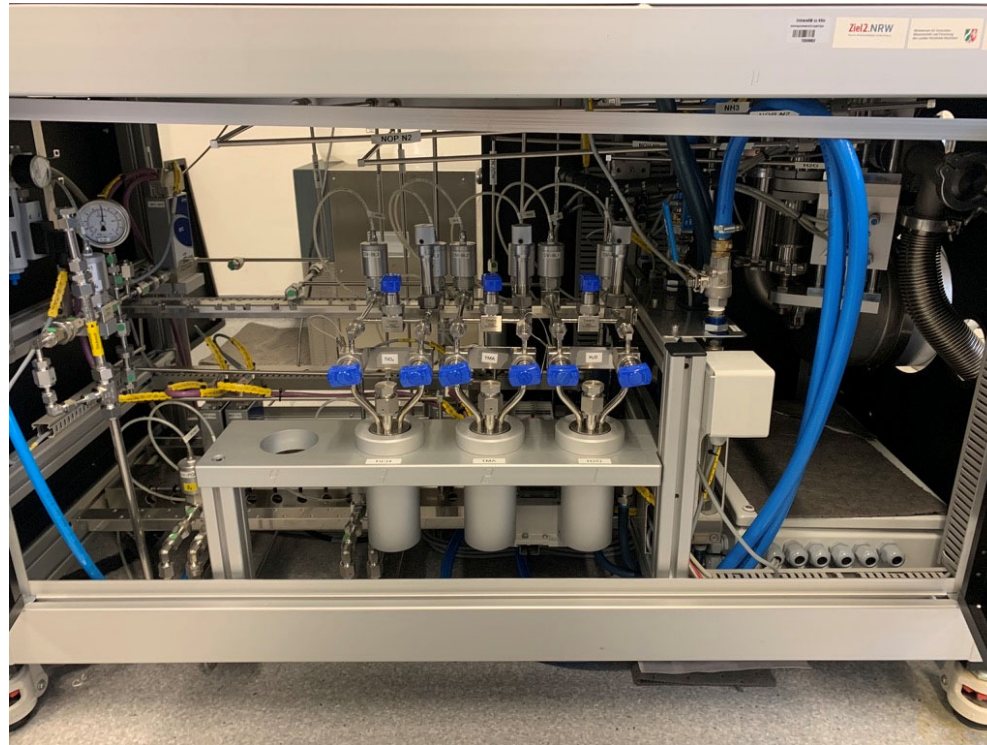
total **high**: ca. 200 cm

ALD, Glove box and airlock are connected. Laptop trolley can be freely moved or replaced.

Details



ALD reaction chamber



liquid sources and gas lines



plasma reaction chamber